



# The 35<sup>th</sup> IEEE International Conference on Microelectronics, (ICM 2023)

Call for Papers, December 17-20, 2023, Abu Dhabi, UAE



The IEEE International Conference on Microelectronics (ICM) has already been held numerous times in different countries across the Middle East, Southern Europe, and Asia for the past 34 years. The 35th edition of the conference will take place in Abu Dhabi-UAE. This edition of ICM will foster oral and poster sessions, industrial panel discussions, and tutorials given by experts on state-of-the-art topics. The regular technical program will run for three days. The tutorial sessions will be held on the first day of the conference. Papers are solicited in, but not limited to, the following topics:

## Circuits and Systems

- Analog and RF circuit design techniques
- Digital signal and data processing
- Wireless communication systems
- Nonlinear circuits
- System on Chip (SoCs)
- VLSI for Signal and Image Processing
- Integrated antenna and front-end co-design
- Signal Processing in Communications

## CAD Tools and Design

- Simulation (process, device, circuit, logic, timing, functional)
- Layout (placement, routing, floor planning, symbolic, ERC, DRC)
- Silicon optimization
- Parallel embedded systems
- Testing: Formal verification
- CAD for FPGAs
- High level synthesis tools
- Design for testability.

## Micro/Nanoelectronics

- Device characterization and modelling
- Device physics and novel structures
- Process technology, CMOS, BJT,
- BiCMOS, GaAs
- Reliability and failure analysis
- Optoelectronics
- MEMS Devices
- Packaging and surface mount technology.

- Accepted and presented papers will be sent to IEEE for inclusion in the IEEE Xplore.
- Prospective authors are invited to submit full length paper (4-page 2-column IEEE format) including results, figures and references using the [IEEE template format](#)
- Paper submission process should be done through EDAS review tool: <https://edas.info>
- More info could be obtained through the conference website at the following link: <http://www.ieee-icm2023.org>
- Authors of top quality presented papers will be invited to submit extended version to be published in a Elsevier journal.
- Authors of accepted papers who will present at the conference but have financial difficulties, as they are from low-income countries, can submit a request for financial support, which is up to a 50% reduction in the full registration fees. Further information will be provided in the paper acceptance notification.

## Important Dates:

Submission of Special Sessions Proposals:	Sept. 30, 2023
Submission of Tutorials Proposals:	Sept. 30, 2023
Submission of Regular / Student Papers:	Sept. 30, 2023
Notification of Tutorials Proposals Acceptance:	Oct. 12, 2023
Notification of Special Sessions Proposals Acceptance:	Oct. 12, 2023
Notification of Paper Acceptance:	Oct. 12, 2023
Camera Ready Submission:	Nov. 12, 2023

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